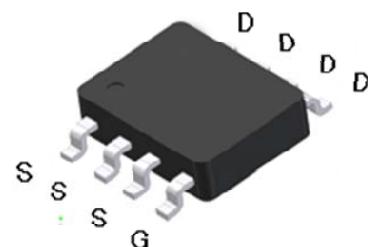
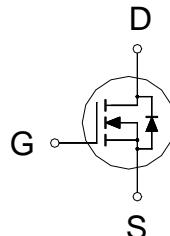


N-Channel Logic Level Enhancement Mode Field Effect Transistor
Product Summary:

BV_{DSS}	200V
$R_{DS(on)}$ (MAX.)	0.5Ω
I_D	1.6A



UIS, 100% Tested

Pb-Free Lead Plating & Halogen Free


ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNIT
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current	I_D	1.6	A
		1	
Pulsed Drain Current ¹	I_{DM}	6.4	
Power Dissipation	P_D	2.5	W
		1	
Operating Junction & Storage Temperature Range	T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$	25	50	°C / W
Junction-to-Ambient ³	$R_{\theta JA}$			

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

³50°C / W when mounted on a 1 in² pad of 2 oz copper.

ELECTRICAL CHARACTERISTICS ($T_c = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	200			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	3.0	4.0	5.0	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 30\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 160\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
		$V_{\text{DS}} = 130\text{V}, V_{\text{GS}} = 0\text{V}, T_j = 125^\circ\text{C}$			25	
On-State Drain Current ¹	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = 5\text{V}, V_{\text{GS}} = 10\text{V}$	1.6			A
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 10\text{V}, I_D = 0.8\text{A}$		0.4	0.5	Ω
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 5\text{V}, I_D = 0.8\text{A}$		2		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1\text{MHz}$		803		pF
Output Capacitance	C_{oss}			19		
Reverse Transfer Capacitance	C_{rss}			16		
Total Gate Charge ^{1,2}	Q_g	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 0.8\text{A}$		21.3		nC
Gate-Source Charge ^{1,2}	Q_{gs}			2.9		
Gate-Drain Charge ^{1,2}	Q_{gd}			6		
Turn-On Delay Time ^{1,2}	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = 100\text{V}, I_D = 0.5\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GS}} = 6\Omega$		20		nS
Rise Time ^{1,2}	t_r			60		
Turn-Off Delay Time ^{1,2}	$t_{\text{d}(\text{off})}$			20		
Fall Time ^{1,2}	t_f			50		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_c = 25^\circ\text{C}$)						
Continuous Current	I_s				1.6	A
Pulsed Current ³	I_{SM}				6.4	
Forward Voltage ¹	V_{SD}	$I_F = I_s, V_{\text{GS}} = 0\text{V}$			1.5	V

¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.

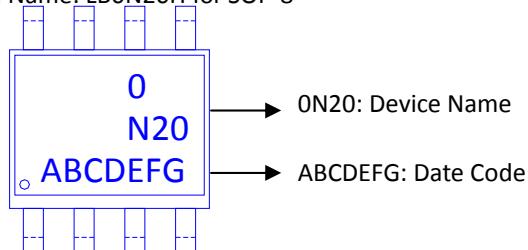
²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

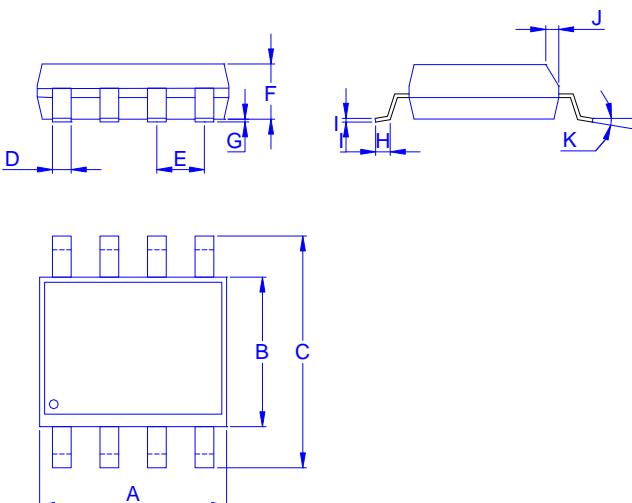
Ordering & Marking

Information:

Device Name: LB0N20H for SOP-8



Outline Drawing



Dimension in mm

Dimension	A	B	C	D	E	F	G	H	I	J	K
in.	4.70	3.70	5.80	0.33		1.20	0.08	0.40	0.19	0.25	0°
Typ.					1.27						
Max.	5.10	4.10	6.20	0.51		1.62	0.28	0.83	0.26	0.50	8°

TYPICAL CHARACTERISTICS

